







LM139, LM239, LM339, LM339B, LM139A, LM239A LM339A, LM2901B, LM2901, LM2901AV, LM2901V SLCS006X - OCTOBER 1979 - REVISED OCTOBER 2023

# LM339B, LM2901B, LM339, LM239, LM139, LM2901 Quad Differential Comparators

#### 1 Features

- NEW LM339B and LM2901B
- Improved specifications of B-version
  - Maximum rating: up to 38 V
  - ESD rating (HBM): 2k V
  - Low input offset: 0.37 mV
  - Low input bias current: 3.5 nA
  - Low supply-current: 200 μA per comparator
  - Faster response time of 1 µsec
  - Extended temperature range for LM339B
- B-version is drop-in replacement for LM239, LM339 and LM2901, A and V versions
- Common-mode input voltage range includes around
- Differential input voltage range equal to maximumrated supply voltage: ±38 V
- Low output saturation voltage
- Output compatible with TTL, MOS, and CMOS
- For single version, see the TL331B
- For dual version, see the LM393B or LM2903B

# 2 Applications

- Vacuum robot
- Single phase UPS
- Server PSU
- Cordless power tool
- Wireless infrastructure
- **Applicances**
- **Building automation**
- Factory automation & control
- Motor drives
- Infotainment & cluster

# 3 Description

The LM339B and LM2901B devices are the next generation versions of the industry-standard LM339 and LM2901 comparator family. These next generation B-version comparators feature lower offset voltage, higher supply voltage capability, lower supply current, lower input bias current, lower propagation delay, and improved 2 kV ESD performance and input ruggedness through dedicated ESD clamps. The LM339B and LM2901B can drop-in replace the LM239, LM339 and LM2901, for both "A" and "V" grades.

All devices consist of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages.

#### **Device Information**

PART NUMBER	PACKAGE (1)	BODY SIZE (NOM)				
LM139x	CDIP (14)	21.30 mm × 7.60 mm				
LM139x, LM239x, LM339x, LM2901x, LM339B, LM2901B	SOIC (14)	8.70 mm × 3.90 mm				
LM239, LM339x, LM2901	PDIP (14)	19.30 mm × 6.40 mm				
LM239, LM2901, LM339B, LM2901B	TSSOP (14)	5.00 mm × 4.40 mm				
LM339x, LM2901, LM339B, LM2901B	SO (14)	10.20 mm × 5.30 mm				
LM339x, LM339B	SSOP (14)	6.50 mm × 5.30 mm				
LM2901B	SOT-23 (14)	4.20 mm x 2.00 mm				
LM339B, LM2901B	WQFN (16)	3.00 mm x 3.00 mm				

For all available packages, see the orderable addendum at the end of the data sheet.

#### **Family Comparison Table**

Specification	LM339B	LM2901B	LM339 LM339A	LM2901 LM2901A	LM2901V LM2901AV	LM139 LM139A	LM239 LM239A	Units
Supply Voltage	2 to 36	2 to 36	2 to 30	2 to 30	2 to 32	2 to 30	2 to 30	V
Total Supply Current (5V to 36V max)	0.8 to 1	0.8 to 1	1 to 2.5	1 to 2.5	1 to 2.5	1 to 2.5	1 to 2.5	mA
Temperature Range	-40 to 85	-40 to 125	0 to 70	-40 to 125	-40 to 125	-55 to 125	-25 to 85	°C
ESD (HBM)	2000	2000	1000	1000	1000	1000	1000	V
Offset Voltage (Max over temp)	± 5.5	± 5.5	± 9 ± 4	± 15 ± 4	± 15 ± 4	± 9 ± 4	± 9 ± 4	mV
Input Bias Current (typ / max)	3.5 / 25	3.5 / 25	25 / 250	25 / 250	25 / 250	25 / 100	25 / 250	nA
Response Time (typ)	1	1	1.3	1.3	1.3	1.3	1.3	µsec



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# **4 Revision History**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	nanges from Revision W (October 2023) to Revision X (October 2023)	Page
•	Added LM339B and LM2901B to Device Information Table for SOT-23/QFN	1
CI	hanges from Revision V (December 2022) to Revision W (October 2023)	Page
•	Updated thermal tables for new package releases	6
•	Changed Apps Input Voltage Range text to reference appnote	<mark>24</mark>
CI	hanges from Revision U (November 2018) to Revision V (December 2022)	Page
•	Updated the numbering format for tables, figures, and cross-references throughout the document	1
•	Added "B" version throughout. Added Device Family Table.	
CI	hanges from Revision T (June 2015) to Revision U (November 2018)	Page
•	Changed LM239x temperature range from 125°C to 85°C in <i>Description</i> section	1
•	Changed data sheet title	<mark>1</mark>
•	Changed LM293AD to LM239AD in Device Comparison Table	4
•	Added Input Current and related footnote in Absolute Maximum Ratings	6
•	Changed layout of Recommended Operating Conditions temperatures to separate rows	
•	Changed values in the Thermal Information table to align with JEDEC standards	8
•	Added LM2901V and LMV2901AV to LM2901 Elect Char Table title to make more clear which devices covered	s are 13
•	Changed "Dual" to "Quad" and removed "Absolute Maximum" wording and mention of Q100 in <i>Overv</i> section text	
	Changed and corrected text in <i>Feature Description</i> section	
	Changed Example Values in <i>Typical Application Design Parameters</i> table	
•	Added Receiving Notification of Documentation Updates section	
CI	hanges from Revision S (August 2012) to Revision T (June 2015)	Page
•	Deleted Ordering Information table.	1
•	Added Military Disclaimer to Features list	1
•	Added Applications, Device Information table, Pin Configuration and Functions section, ESD Ratings Thermal Information table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. No	table,
	specification changes	1



# **5 Other Versions**

# OTHER QUALIFIED VERSIONS OF LM139-SP, LM239A, LM2901, LM2901AV, LM2901V:

Automotive Q100: LM239A-Q1, LM2901B-Q1, LM2901-Q1, LM2901AV-Q1, LM2901V-Q1

Enhanced Product: LM239A-EP

Space: LM139-SP



# **6 Pin Configuration and Functions**

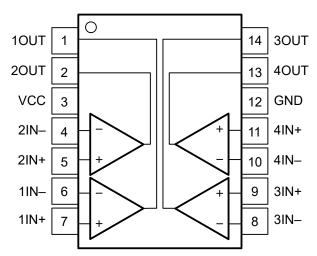
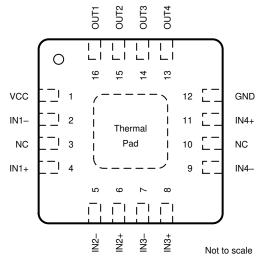


Figure 6-1. D, DB, N, NS, PW, DYY, J Packages 14-Pin SOIC, SSOP, PDIP, SO, TSSOP, SOT-23, CDIP Top View



NOTE: Connect exposed thermal pad directly to GND pin.

Figure 6-2. RTE Package 16-Pad WQFN With Exposed Thermal Pad Top View

Table 6-1. Pin Functions

	PIN			
NAME <sup>(1)</sup>	D, DB, N, NS, PW, DYY, J	WQFN	1/0	DESCRIPTION
OUT1 <sup>(1)</sup>	1	16	Output	Output pin of the comparator 2
OUT2 (1)	2	15	Output	Output pin of the comparator 1
V <sub>CC</sub>	3	1	_	Positive supply
IN2- <sup>(1)</sup>	4	5	Input	Negative input pin of the comparator 1
IN2+ <sup>(1)</sup>	5	6	Input	Positive input pin of the comparator 1
IN1- <sup>(1)</sup>	6	2	Input	Negative input pin of the comparator 2
IN1+ <sup>(1)</sup>	7	4	Input	Positive input pin of the comparator 2
IN3-	8	7	Input	Negative input pin of the comparator 3
IN3+	9	8	Input	Positive input pin of the comparator 3
IN4-	10	9	Input	Negative input pin of the comparator 4
IN4+	11	11	Input	Positive input pin of the comparator 4
GND	12	12	_	Negative supply
OUT4	13	13	Output	Output pin of the comparator 4
OUT3	14	14	Output	Output pin of the comparator 3
NC	_	3	_	No Internal Connection - Leave floating or GND
NC	_	10	_	No Internal Connection - Leave floating or GND
Thermal Pad	_	PAD	_	Connect directly to GND pin

<sup>(1)</sup> Some manufacturers transpose the names of channels 1 & 2. Electrically the pinouts are identical, just a difference in the channel naming convention.



# 7 Specifications

# 7.1 Absolute Maximum Ratings for LM339B and LM2901B

over operating free-air temperature range (unless otherwise noted)(1)

	MIN	MAX	UNIT
Supply voltage: $V_S = (V+) - (V-)$	-0.3	38	V
Differential input voltage : V <sub>ID</sub> <sup>(2)</sup>		±38	V
Input pins (IN+, IN-)	-0.3	38	V
Current into input pins (IN+, IN-)		-50	mA
Output pin (OUT)	-0.3	38	V
Output sink current		25	mA
Output short-circuit duration <sup>(3)</sup>		Unlimited	S
Junction temperature, T <sub>J</sub>	TBD	150	°C
Storage temperature, T <sub>stg</sub>	-65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Differential voltages are at IN+ with respect to IN-
- (3) Short circuits from outputs to V+ can cause excessive heating and eventual destruction.

# 7.2 Absolute Maximum Ratings for Non-B Versions

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage <sup>(2)</sup>			36	V
$V_{\text{ID}}$	Differential input voltage <sup>(3)</sup>			±36	V
VI	Input voltage range (either input)		-0.3	36	V
I <sub>K</sub>	Input current <sup>(5)</sup>			-50	mA
Vo	Output voltage			36	V
Io	Output current			20	mA
	Duration of output short circuit to ground <sup>(4)</sup>		Unlir	nited	
TJ	Operating virtual-junction temperature			150	°C
	Case temperature for 60 s	FK package		260	°C
	Lead temperature 1.6 mm (1/16 in) from case for 60 s	J package		300	°C
T <sub>stg</sub>	Storage temperature		-65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to network ground.
- (3) Differential voltages are at xIN+ with respect to xIN-.
- (4) Short circuits from outputs to V<sub>CC</sub> can cause excessive heating and eventual destruction.
- (5) Input current flows through parasitic diode to ground and will turn on parasitic transistors that will increase I<sub>CC</sub> and may cause output to be incorrect. Normal operation resumes when input is removed.



## 7.3 ESD Ratings for LM339B and LM2901B

				VALUE	UNIT
	V <sub>(ESD)</sub> Electrostatic discharge	Electrostatic	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
		discharge Human-body mod	Human-body model (CDM), per ANSI/ESDA/JEDEC JS-002 <sup>(2)</sup>	±1000	V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process

# 7.4 ESD Ratings, Non-B Versions

			VALUE	UNIT
V	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>		V
V <sub>(ESD)</sub>	Liectiostatic discriarge	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±750	<b>v</b>

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.5 Recommended Operating Conditions for LM339B and LM2901B

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Supply voltage: V <sub>S</sub> = (V+) – (V–)	2	36	V
Ambient temperature, T <sub>A,</sub> LM339B	-40	85	°C
Ambient temperature, T <sub>A,</sub> LM2901B	-40	125	°C
Input Voltage Range, V <sub>IVR</sub>	(V-) - 0.1	(V+) - 2.0	V

# 7.6 Recommended Operating Conditions, Non-B Versions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	Non-V devices	2	30	V
	Supply voltage	V devices	2	32	V
TJ		LM139x	<b>-</b> 55	125	
	Junction temperature	LM239x	-25	85	°c
	Juliculon temperature	LM339x	-0	70	
		LM2901x	-40	125	



### 7.7 Thermal Information for LM339B and LM2901B

			LM339B, LM2901B					
THERMAL METRIC(1)			PW (TSSOP)	DDY (SOT-23)	RUC (QFN)	RTE (QFN)	UNIT	
			14 PINS	14 PINS	14 PINS	16 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	111.2	136.6			67.6	°C/W	
R <sub>0JC(top)</sub>	Junction-to-case (top) thermal resistance	66.9	66.6			72.3	°C/W	
$R_{\theta JB}$	Junction-to-board thermal resistance	67.8	79.8			43.1	°C/W	
ΨЈТ	Junction-to-top characterization parameter	28.0	17.8			6.3	°C/W	
ΨЈВ	Junction-to-board characterization parameter	67.4	79.3			42.8	°C/W	
R <sub>0JC(bot)</sub>	Junction-to-case (bottom) thermal resistance	-	-	-		26.4	°C/W	

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semicondctor and IC Package Thermal Metrics report, SPRA953.

### 7.8 Thermal Information for Non-B Versions

	THERMAL METRIC <sup>(1)</sup>	D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	(CDIP)	W (CFP)	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	98.8	111.8	79	96.2	120	89.5	156.2	°C/W
R <sub>0JC(top)</sub>	Junction-to-case (top) thermal resistance	64.3	63.6	73.4	56.1	59	46.1	86.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	59.7	60.5	58.7	56.9	68.8	78.7	154.6	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	25.7	26.2	48.3	24.8	9.9	3	56.5	°C/W
ΨЈВ	Junction-to-board characterization parameter	59.3	59.8	58.5	56.4	68.2	71.8	133.5	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	_	_	-	-	_	24.2	14.3	°C/W

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



### 7.9 Electrical Characteristics for LM339B

 $V_S = 5 \text{ V}, V_{CM} = (V-)$ ;  $T_A = 25^{\circ}\text{C}$  (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V.	Input offset voltage	V <sub>S</sub> = 5 to 36V	-3.5	±0.37	3.5	mV
V <sub>IO</sub>	input onset voltage	V <sub>S</sub> = 5 to 36V, T <sub>A</sub> = -40°C to +85°C	-5.5		5.5	IIIV
L	Input bias current			-3.5	-25	nA
I <sub>B</sub>	input bias current	$T_A = -40$ °C to +85°C			-50	nA
l	Input offset current		-25	±0.5	25	nA
los	input onset current	$T_A = -40$ °C to +85°C	-50		50	nA
V	Common mode range (1)	V <sub>S</sub> = 3 to 36V	(V-)		(V+) – 1.5	V
V <sub>CM</sub>	Common mode range V	V <sub>S</sub> = 3 to 36V, T <sub>A</sub> = -40°C to +85°C	(V-)		(V+) - 2.0	V
A <sub>VD</sub>	Large signal differential voltage amplification (2)	$V_S = 15V$ , $V_O = 1.4V$ to 11.4V; $R_L \ge 15k$ to (V+)	50	200		V/mV
	Low level output Voltage	I <sub>SINK</sub> ≤ 4mA, V <sub>ID</sub> = -1V		110	400	mV
V <sub>OL</sub>	{swing from (V–)}	$I_{SINK} \le 4\text{mA}, V_{ID} = -1V$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			550	mV
	High-level output leakage current	$(V+) = V_O = 5 V; V_{ID} = 1V$		0.1	50	nA
I <sub>OH-LKG</sub>	nigri-ievei output leakage current	(V+) = V <sub>O</sub> = 36V; V <sub>ID</sub> = 1V			100	nA
I <sub>OL</sub>	Low level output current	$V_{OL} = 1.5V; V_{ID} = -1V; V_{S} = 5V$	6	21		mA
I.	Quiescent current (all comparators)	V <sub>S</sub> = 5 V, no load		0.8	1.2	mA
IQ	Quiescent current (an comparators)	V <sub>S</sub> = 36 V, no load, T <sub>A</sub> = -40°C to +85°C		1	1.6	mA

<sup>(1)</sup> The voltage at either input should not be allowed to go negative by more than 0.3 V otherwise output may be incorrect and excessive input current can flow. The upper end of the common-mode voltage range is limited by V<sub>CC</sub> – 2V. However only one input needs to be in the valid common mode range, the other input can go up the maximum V<sub>CC</sub> level and the comparator provides a proper output state. Either or both inputs can go to maximum V<sub>CC</sub> level without damage.

<sup>(2)</sup> This parameter is ensured by design and/or characterization and is not tested in production.



#### 7.10 Electrical Characteristics for LM2901B

 $V_S = 5 \text{ V}, V_{CM} = (V_-); T_A = 25^{\circ}\text{C} \text{ (unless otherwise noted)}.$ 

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V.	Input offset voltage	V <sub>S</sub> = 5 to 36V	-3.5	±0.37	3.5	mV
V <sub>IO</sub>	input onset voltage	V <sub>S</sub> = 5 to 36V, T <sub>A</sub> = -40°C to +125°C	-5.5		5.5	IIIV
L	Input bigg ourrent			-3.5	-25	nA
I <sub>B</sub>	Input bias current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			-50	nA
L	Input offset surrent		-25	±0.5	25	nA
I <sub>OS</sub>	Input offset current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	-50		50	nA
V	Common mode range (1)	V <sub>S</sub> = 3 to 36V	(V-)		(V+) – 1.5	V
V <sub>CM</sub>	Common mode range V	V <sub>S</sub> = 3 to 36V, T <sub>A</sub> = -40°C to +125°C	(V-)		(V+) - 2.0	V
A <sub>VD</sub>	Large signal differential voltage amplification (2)	$V_S = 15V$ , $V_O = 1.4V$ to 11.4V; $R_L \ge 15k$ to $(V+)$	50	200		V/mV
	Low lovel output Veltage	I <sub>SINK</sub> ≤ 4mA, V <sub>ID</sub> = -1V		110	400	mV
V <sub>OL</sub>	Low level output Voltage {swing from (V–)}	$I_{SINK} \le 4mA, V_{ID} = -1V$ $T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			550	mV
	High level output leakage current	(V+) = V <sub>O</sub> = 5 V; V <sub>ID</sub> = 1V		0.1	50	nA
I <sub>OH-LKG</sub>	High-level output leakage current	(V+) = V <sub>O</sub> = 36V; V <sub>ID</sub> = 1V			100	nA
I <sub>OL</sub>	Low level output current	V <sub>OL</sub> = 1.5V; V <sub>ID</sub> = -1V; V <sub>S</sub> = 5V	6	21		mA
	Quiescent current (all comparators)	V <sub>S</sub> = 5 V, no load		0.8	1.2	mA
IQ	Quiescent current (all comparators)	V <sub>S</sub> = 36 V, no load, T <sub>A</sub> = -40°C to +125°C		1	1.6	mA

<sup>(1)</sup> The voltage at either input should not be allowed to go negative by more than 0.3 V otherwise output may be incorrect and excessive input current can flow. The upper end of the common-mode voltage range is limited by  $V_{CC} - 2V$ . However only one input needs to be in the valid common mode range, the other input can go up the maximum  $V_{CC}$  level and the comparator provides a proper output state. Either or both inputs can go to maximum  $V_{CC}$  level without damage.

<sup>(2)</sup> This parameter is ensured by design and/or characterization and is not tested in production.



### 7.11 Electrical Characteristics for LM139 and LM139A

at specified free-air temperature, V<sub>CC</sub> = 5 V (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS <sup>(1)</sup>	T <sub>A</sub> (2)	LM <sup>2</sup>	139		LM1	139A		UNIT
	PARAIVIETER	TEST CON	IDITIONS.	I A (-/	MIN	TYP	MAX	MIN	TYP	MAX	UNII
.,		$V_{CC} = 5 \text{ V to}$		25°C		2	5		1	2	.,
V <sub>IO</sub>	Input offset voltage	$V_{IC} = V_{ICR} \text{ mi}$ $V_{O} = 1.4 \text{ V}$	n,	Full range			9			4	mV
1	Input offset current	\/_ = 1 4 \/	r <sub>O</sub> = 1.4 V			3	25		3	25	nA
I <sub>IO</sub>	input onset current	VO - 1.4 V					100			100	ПА
1	Input bias current	V <sub>O</sub> = 1.4 V		25°C		-25	-100		-25	-100	nA
I <sub>IB</sub>	input bias current	VO - 1.4 V		Full range			-300			-300	IIA
V	Common-mode input-				0 to V <sub>CC</sub> - 1.5			0 to V <sub>CC</sub> - 1.5			V
V <sub>ICR</sub>	voltage range <sup>(3)</sup>			Full range	0 to V <sub>CC</sub> - 2			0 to V <sub>CC</sub> - 2			v
A <sub>VD</sub>	Large-signal differential- voltage amplification	$V_{CC+} = \pm 7.5 \ V_{O} = -5 \ V \text{ to}$		25°C		200		50	200		V/mV
1	High-level output current	V <sub>ID</sub> = 1 V	V <sub>OH</sub> = 5 V	25°C		0.1			0.1		nA
I <sub>OH</sub>	riigii-ievei output current	VID - 1 V	V <sub>OH</sub> = 30 V	Full range			1			1	μΑ
V <sub>OL</sub>	Low-level output voltage	V <sub>ID</sub> = -1 V,	I <sub>OI</sub> = 4 mA	25°C		150	400		150	400	mV
VOL	Low-level output voltage	VID = -1 V,	10L - 4 111A	Full range			700			700	1117
I <sub>OL</sub>	Low-level output current	$V_{ID} = -1 V$ ,	V <sub>OL</sub> = 1.5 V	25°C	6	16		6	16		mA
I <sub>CC</sub>	Supply current (four comparators)	V <sub>O</sub> = 2.5 V,	No load	25°C		0.8	2		0.8	2	mA

<sup>(1)</sup> All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

<sup>(2)</sup> Full range (MIN to MAX) for LM139 and LM139A is –55°C to +125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

<sup>(3)</sup> The voltage at either input or common-mode must not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V<sub>CC+</sub> – 1.5 V; however, one input can exceed V<sub>CC</sub>, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.



### 7.12 Electrical Characteristics for LMx39 and LMx39A

at specified free-air temperature, V<sub>CC</sub> = 5 V (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS <sup>(1)</sup>	T <sub>A</sub> <sup>(2)</sup>	LM: LM:				39A 39A		UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
.,		$V_{CC} = 5 \text{ V to } 30$		25°C		2	5		1	3	.,
V <sub>IO</sub>	Input offset voltage	$V_{IC} = V_{ICR} min$ $V_{O} = 1.4 V$		Full range			9			4	mV
I <sub>IO</sub>	Input offset current	V <sub>O</sub> = 1.4 V		25°C		5	50		5	50	nA
יוט	input onset current	VO = 1.4 V	0 - 1.4 V				150			150	ПА
I <sub>IB</sub>	Input bias current	V <sub>O</sub> = 1.4 V		25°C		-25	-250		-25	-250	nA
ıВ	input bias current	VO = 1.4 V	0 = 1.4 V				-400			-400	11/4
V	Common-mode input-				0 to V <sub>CC</sub> - 1.5			0  to V <sub>CC</sub> $-1.5$			V
V <sub>ICR</sub>	voltage range <sup>(3)</sup>			Full range	0 to V <sub>CC</sub> - 2			0 to V <sub>CC</sub> - 2			v
A <sub>VD</sub>	Large-signal differential- voltage amplification	$V_{CC}$ = 15 V, $V_{O}$ = 1.4 V to 1 $R_{L}$ ≥ 15 k $\Omega$ to		25°C	50	200		50	200		V/mV
la	High-level output current	V <sub>ID</sub> = 1 V	V <sub>OH</sub> = 5 V	25°C		0.1	50		0.1	50	nA
I <sub>OH</sub>	riigii-ievei output current	VID - I V	V <sub>OH</sub> = 30 V	Full range			1			1	μΑ
V <sub>OL</sub>	Low-level output voltage	V <sub>ID</sub> = -1 V,	I <sub>OL</sub> = 4 mA	25°C		150	400		150	400	mV
V OL	Low-level output voltage	V <sub>ID</sub> = -1 V,	10L - 4 111A	Full range			700			700	1110
I <sub>OL</sub>	Low-level output current	V <sub>ID</sub> = −1 V,	V <sub>OL</sub> = 1.5 V	25°C	6	16		6	16		mA
I <sub>CC</sub>	Supply current (four comparators)	V <sub>O</sub> = 2.5 V,	No load	25°C		0.8	2		0.8	2	mA

<sup>(1)</sup> All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

<sup>(2)</sup> Full range (MIN to MAX) for LM239/LM239A is -25°C to +85°C, and for LM339/LM339A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

<sup>(3)</sup> The voltage at either input or common-mode must not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V<sub>CC+</sub> – 1.5 V; however, one input can exceed V<sub>CC</sub>, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.



# 7.13 Electrical Characteristics for LM2901, LM2901V and LM2901AV

at specified free-air temperature,  $V_{CC}$  = 5 V (unless otherwise noted)

	DADAMETED	TEST COND	UTIONS(1)	<b>-</b> (2)	LM2	901		UNIT
	PARAMETER	1EST COND	ITIONS	T <sub>A</sub> <sup>(2)</sup>	MIN	TYP	MAX	UNII
			Non-A devices	25°C		2	7	
.,	Input offeet veltere	$V_{IC} = V_{ICR} min,$	Non-A devices	Full range			15	mV
V <sub>IO</sub>	Input offset voltage	$V_O = 1.4 \text{ V},$ $V_{CC} = 5 \text{ V to MAX}^{(3)}$	A-suffix devices	25°C		1	2	IIIV
			A-sum devices	Full range			4	
	Innut offeet ourrent	V = 4.4 V		25°C		5	50	nA
I <sub>IO</sub>	Input offset current	V <sub>O</sub> = 1.4 V	) - 1.4 V				200	ΠA
	Input bigg gurrent	V = 4.4 V		25°C		-25	-250	n 1
I <sub>IB</sub>	Input bias current	V <sub>O</sub> = 1.4 V		Full range			-500	nA
V	Common-mode input-			25°C	0 to V <sub>CC</sub> - 1.5			V
VICR	V <sub>ICR</sub> voltage range <sup>(4)</sup>			Full range	0 to V <sub>CC</sub> - 2			V
A <sub>VD</sub>	Large-signal differential- voltage amplification	$V_{CC}$ = 15 V, $V_{O}$ = 1.4 V to $R_{L} \ge$ 15 k $\Omega$ to $V_{CC}$	o 11.4 V,	25°C	25	100		V/mV
	High-level output current	V <sub>ID</sub> = 1 V	V <sub>OH</sub> = 5 V	25°C		0.1	50	nA
I <sub>OH</sub>	nigri-level output current	VID - I V	$V_{OH} = V_{CC} MAX^{(3)}$	Full range			1	μA
			Non-V devices	25.0		150	500	
V <sub>OL</sub>	Low-level output voltage	$V_{ID} = -1 V$ , $I_{OL} = 4 \text{ mA}$	V-suffix devices	- 25°C		150	400	mV
		IOL THURK	All devices	Full range			700	
I <sub>OL</sub>	Low-level output current	V <sub>ID</sub> = -1 V,	V <sub>OL</sub> = 1.5 V	25°C	6	16		mA
	Supply current	V <sub>O</sub> = 2.5 V,	V <sub>CC</sub> = 5 V	25°C		0.8	2	mA
I <sub>CC</sub>	(four comparators)	No load	$V_{CC} = MAX^{(3)}$	250		1	2.5	ША

- (1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (2) Full range (MIN to MAX) for LM2901 is –40°C to +125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (3) V<sub>CC</sub> MAX = 30 V for non-V devices, and 32 V for V-suffix devices
- (4) The voltage at either input or common-mode must not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V<sub>CC+</sub> 1.5 V; however, one input can exceed V<sub>CC</sub>, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to V<sub>CC</sub> MAX without damage.



# 7.14 Switching Characteristics for LM139 and LM139A

 $V_{CC}$  = 5 V,  $T_A$  = 25°C

PARAMETER	TEST COI	NDITIONS	LM139 LM139A	UNIT
		TYP		
Response time	$R_L$ connected to 5 V through 5.1 k $\Omega$ ,	100-mV input step with 5-mV overdrive	1.3	
Iveshouse mile	$C_L = 15 \text{ pF}^{(1)} (2)$	TTL-level input step	0.3	μs

- (1) C<sub>L</sub> includes probe and jig capacitance.
- (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

#### 7.15 Switching Characteristics for LM339B and LM2901B

 $V_S = 5V$ ,  $V_{OPULLUP} = 5V$ ,  $V_{CM} = V_S/2$ ,  $C_L = 15pF$ ,  $R_L = 5.1k$  Ohm,  $T_A = 25^{\circ}C$  (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>response</sub>	Propagation delay time, high-to-low; Small scale input signal <sup>(1)</sup>	Input overdrive = 5mV, Input step = 100mV		1000		ns
t <sub>response</sub>	Propagation delay time, high-to-low; TTL input signal <sup>(1)</sup>	TTL input with V <sub>ref</sub> = 1.4V		300		ns

(1) High-to-low and low-to-high refers to the transition at the input.

# 7.16 Switching Characteristics for LMx39 and LMx39A

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ 

PARAMETER	TEST CONE	DITIONS	LM239 LM239A LM339 LM339A	UNIT
			TYP	
Response time	$R_L$ connected to 5 V through 5.1 kΩ, $C_L$ = 15 pF <sup>(1)</sup> (2)	100-mV input step with 5-mV overdrive	1.3	
	$C_L = 15 \text{ pF}^{(1)} (2)$	0.3	μs	

- (1) C<sub>L</sub> includes probe and jig capacitance.
- (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

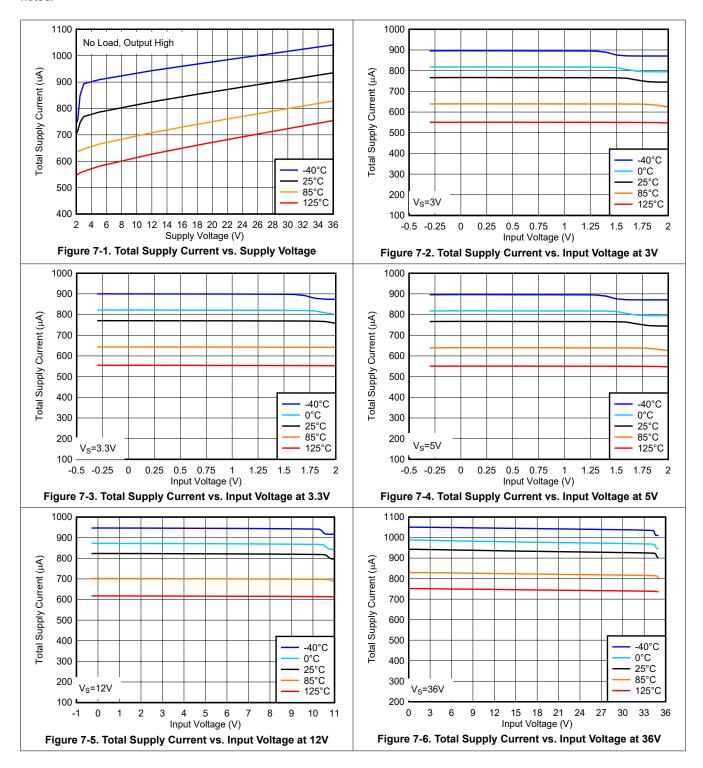
### 7.17 Switching Characteristics for LM2901

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ 

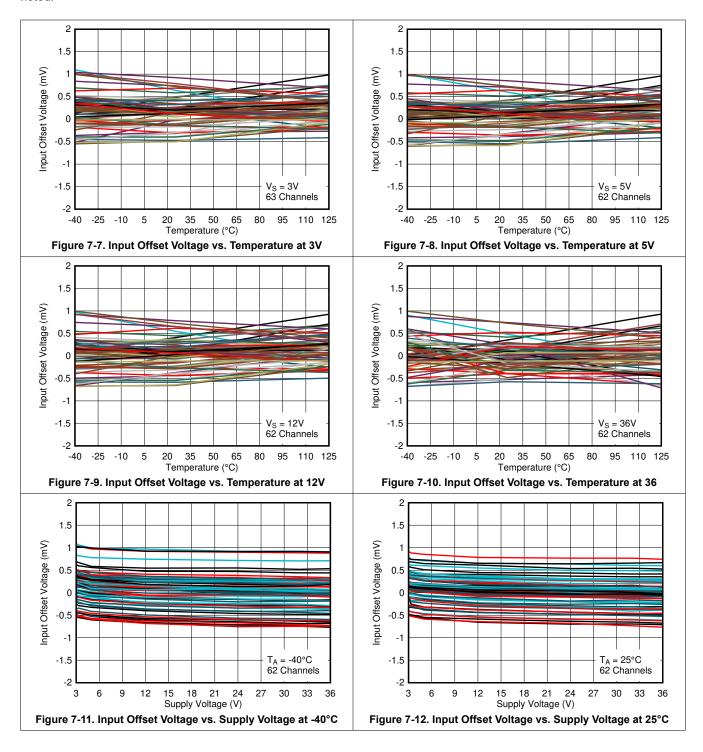
PARAMETER	TEST CON	IDITIONS	LM2901	UNIT
PARAMETER	TEST CON	TYP	UNIT	
Response time	R <sub>L</sub> connected to 5 V through 5.1 kΩ,	100-mV input step with 5-mV overdrive	1.3	
Response unie	$C_L = 15 pF^{(1)}(2)$	TTL-level input step	0.3	μs

- (1) C<sub>L</sub> includes probe and jig capacitance.
- (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

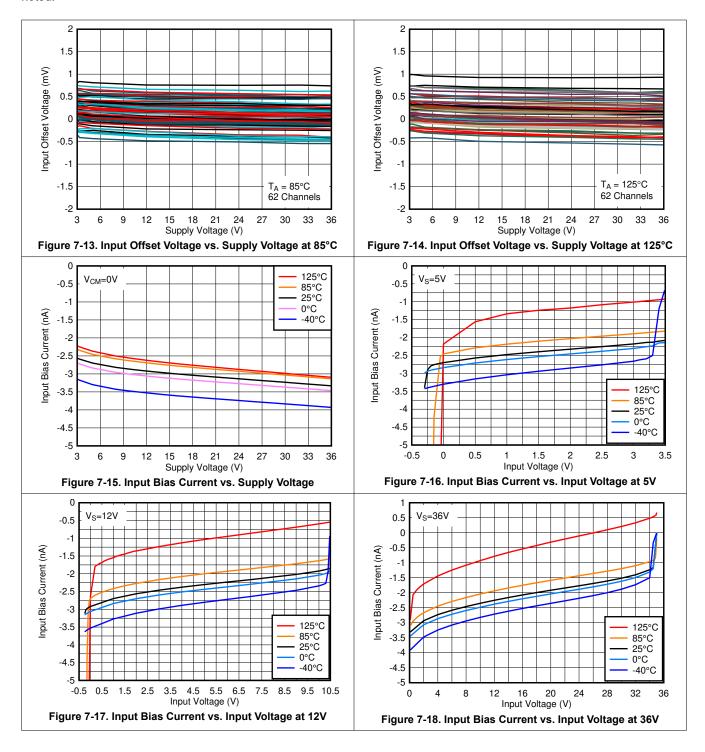




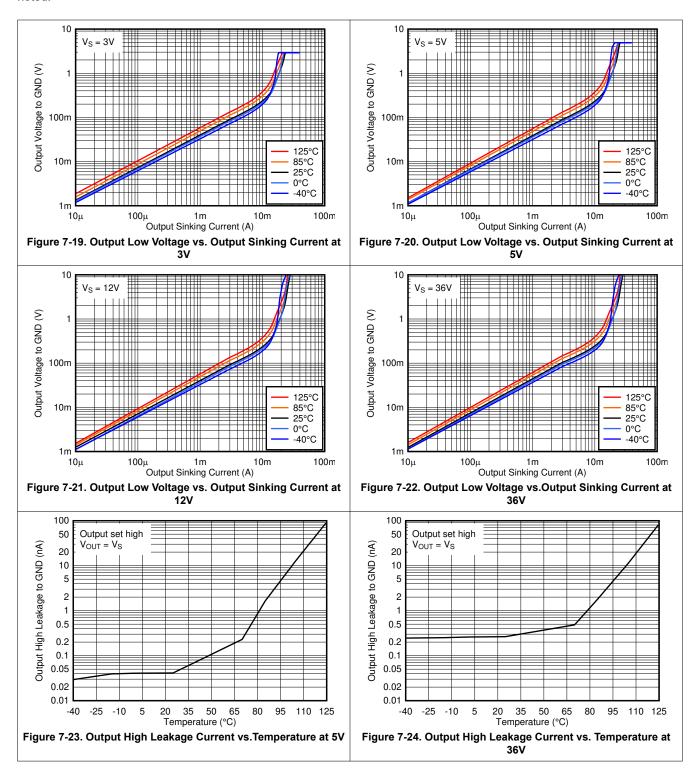




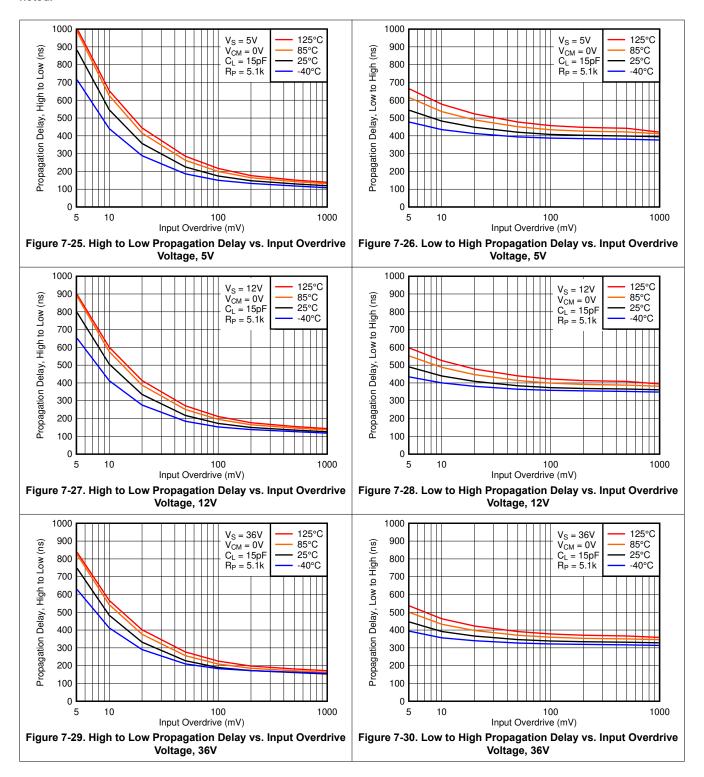














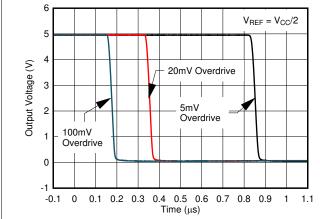


Figure 7-31. Response Time for Various Overdrives, High-to-Low Transition

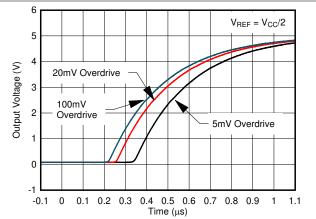


Figure 7-32. Response Time for Various Overdrives, Low-to-High Transition



# 7.19 Typical Characteristics, Non-B Versions

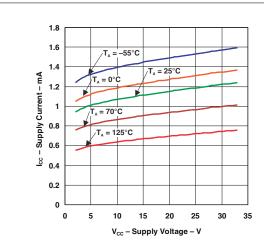


Figure 7-33. Supply Current vs Supply Voltage

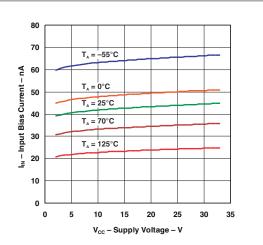


Figure 7-34. Input Bias Current vs Supply Voltage

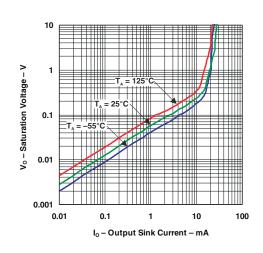


Figure 7-35. Output Saturation Voltage

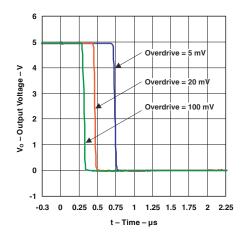
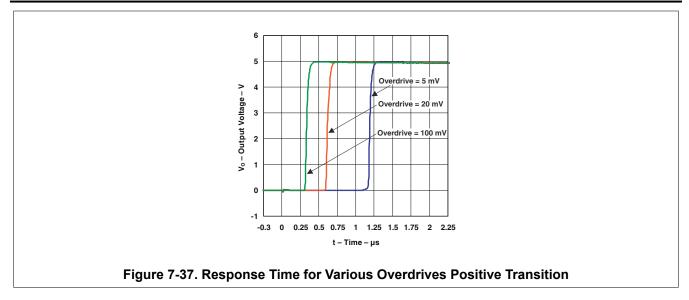


Figure 7-36. Response Time for Various Overdrives

Negative Transition







# **8 Detailed Description**

#### 8.1 Overview

The LMx39 and LM2901x are quad comparators with the ability to operate up to an absolute maximum of 36 V on the supply pin. This standard device has proven ubiquity and versatility across a wide range of applications. This is due to very wide supply voltages range (2 V up to 32 V), low Iq, and fast response of the device.

The open-drain output allows the user to configure the output logic low voltage (V<sub>OL</sub>) and allows the comparator to be used in AND functionality.

### 8.2 Functional Block Diagram

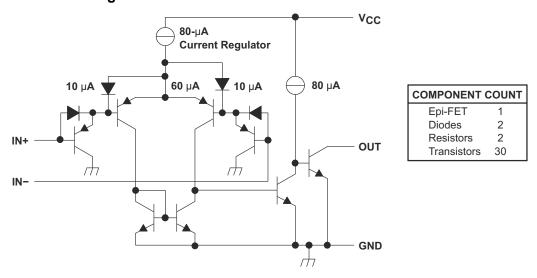


Figure 8-1. Schematic (Each Comparator)

#### 8.3 Feature Description

The comparator consists of a PNP Darlington pair input, allowing the device to operate with very high gain and fast response with minimal input bias current. The input Darlington pair creates a limit on the input common-mode voltage capability, allowing the comparator to accurately function from ground to  $(V_{CC}-1.5\ V)$  differential input. Allow for  $(V_{CC}-2\ V)$  at cold temperature.

The output consists of an open-collector NPN (pulldown or low-side) transistor. The output NPN sinks current when the negative input voltage is higher than the positive input voltage and the offset voltage. The VOL is resistive and scales with the output current. See the Section 7 section for  $V_{OL}$  values with respect to the output current.

#### 8.4 Device Functional Modes

# 8.4.1 Voltage Comparison

The comparator operates solely as a voltage comparator, comparing the differential voltage between the positive and negative pins and outputting a logic low or high impedance (logic high with pullup) based on the input differential polarity.



# 9 Application and Implementation

#### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

Typically, a comparator compares either a single signal to a reference, or to two differnt signals. Many users take advantage of the open-drain output to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes LMx39 or LM2901x optimal for level shifting to a higher or lower voltage.

## 9.2 Typical Application

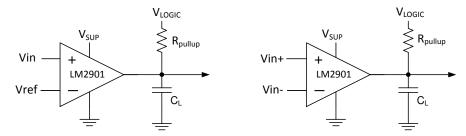


Figure 9-1. Single-ended and Differential Comparator Configurations

#### 9.2.1 Design Requirements

For this design example, use the parameters listed in Table 9-1 as the input parameters.

**DESIGN PARAMETER EXAMPLE VALUE** Input Voltage Range 0 V to Vsup-1.5 V Supply Voltage 4.5 V to V<sub>CC</sub> maximum Logic Supply Voltage 0 V to V<sub>CC</sub> maximum Output Current (R<sub>PULLUP</sub>)  $1 \mu A$  to 4 mAInput Overdrive Voltage 100 mV Reference Voltage 2.5 V Load Capacitance (C<sub>I</sub>) 15 pF

Table 9-1. Design Parameters

# 9.2.2 Detailed Design Procedure

When using the LMx39 in a general comparator application, determine the following:

- Input voltage range
- · Minimum overdrive voltage
- Output and drive current
- Response time

#### 9.2.2.1 Input Voltage Range

When choosing the input voltage range, the input common-mode voltage range ( $V_{ICR}$ ) must be taken in to account. If temperature operation is above or below 25°C the  $V_{ICR}$  can range from 0 V to  $V_{CC}$ – 2 V. This limits the input voltage range to as high as  $V_{CC}$ – 2 V and as low as 0 V. Operation outside of this range can yield incorrect comparisons.



The following list describes the outcomes of some input voltage situations.

- When both IN– and IN+ are both within the common-mode range:
  - If IN- is higher than IN+ and the offset voltage, the output is low and the output transistor is sinking current
  - If IN- is lower than IN+ and the offset voltage, the output is high impedance and the output transistor is not conducting
- When IN– is higher than common mode and IN+ is within common mode, the output is low and the output transistor is sinking current
- When IN+ is higher than common mode and IN- is within common mode, the output is high impedance and the output transistor is not conducting
- When IN- and IN+ are both higher than common mode, see Section 2 of Application Design Guidelines for LM339, LM393, TL331 Family Comparators Including the New B-versions

#### 9.2.2.2 Minimum Overdrive Voltage

Overdrive voltage is the differential voltage produced between the positive and negative inputs of the comparator over the offset voltage ( $V_{IO}$ ). To make an accurate comparison, the overdrive voltage ( $V_{OD}$ ) must be higher than the input offset voltage ( $V_{IO}$ ). Overdrive voltage can also determine the response time of the comparator, with the response time decreasing with increasing overdrive. Figure 9-2 and Figure 9-3 show positive and negative response times with respect to overdrive voltage.

### 9.2.2.3 Output and Drive Current

Output current is determined by the load and pullup resistance and logic and pullup voltage. The output current produces a low-level output voltage ( $V_{OL}$ ) from the comparator, where  $V_{OL}$  is proportional to the output current.

The output current can also effect the transient response.

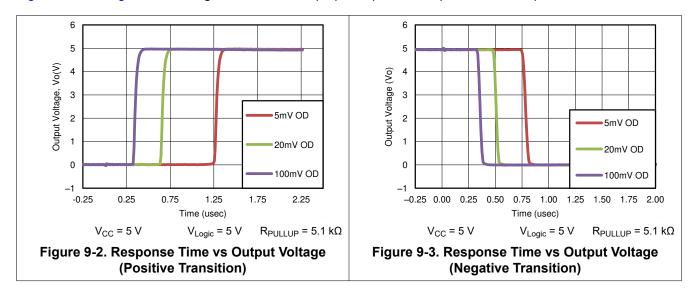
#### 9.2.2.4 Response Time

Response time is a function of input over-drive. See the Section 7.19 graphs for typical response times. The rise and fall times can be determined by the load capacitance ( $C_L$ ), load/pull-up resistance ( $R_{PULLUP}$ ) and equivalent collector-emitter resistance ( $R_{CE}$ ).

- The rise time (τ<sub>R</sub>) is approximately τ<sub>R</sub>~ R<sub>PULLUP</sub> × C<sub>L</sub>
- The fall time (τ<sub>F</sub>) is approximately τ<sub>F</sub> ~ R<sub>CE</sub> × C<sub>L</sub>
  - R<sub>CE</sub> can be determined by taking the slope of Figure 7-35 in its linear region at the desired temperature, or by dividing the V<sub>OL</sub> by I<sub>OUT</sub>

### 9.2.3 Application Curves

Figure 9-2 and Figure 9-3 were generated with scope probe parasitic capacitance of 50 pF.



# 9.3 Power Supply Recommendations

For fast response and comparison applications with noisy or AC inputs, use a bypass capacitor on the supply pin to reject any variation on the supply voltage. This variation can affect the common-mode range of the comparator input and create an inaccurate comparison.

#### 9.4 Layout

# 9.4.1 Layout Guidelines

To create an accurate comparator application without hysteresis, maintain a stable power supply with minimized noise and glitches, which can affect the high level input common-mode voltage range. To achieve this accuracy, add a bypass capacitor between the supply voltage and ground. Place a bypass capacitor on the positive power supply and negative supply (if available).

### Note

If a negative supply is not being used, do not place a capacitor between the GND pin of the device and system ground.

# 9.4.2 Layout Example

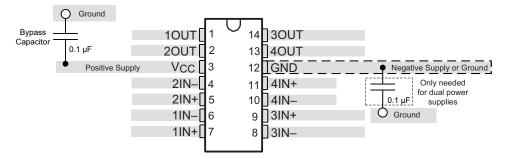


Figure 9-4. LMx39 Layout Example



# 10 Device and Documentation Support

### 10.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 10-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM139	Click here	Click here	Click here	Click here	Click here
LM239	Click here	Click here	Click here	Click here	Click here
LM339	Click here	Click here	Click here	Click here	Click here
LM139A	Click here	Click here	Click here	Click here	Click here
LM239A	Click here	Click here	Click here	Click here	Click here
LM339A	Click here	Click here	Click here	Click here	Click here
LM2901	Click here	Click here	Click here	Click here	Click here
LM2901AV	Click here	Click here	Click here	Click here	Click here
LM2901V	Click here	Click here	Click here	Click here	Click here

## 10.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

# 10.3 Support Resources

TI E2E<sup>™</sup> support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

#### 10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

#### 10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### 10.6 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

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# 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.



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# **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM139AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	LM139A	
LM139ADG4	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	LM139A	
LM139ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	LM139	
LM139DG4	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	LM139	
LM139DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM239AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-25 to 85	LM239A	
LM239ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADRE4	ACTIVE	SOIC	D	14	2500	TBD	Call TI	Call TI	-25 to 85		Samples
LM239ADRG4	ACTIVE	SOIC	D	14	2500	TBD	Call TI	Call TI	-25 to 85		Samples
LM239D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-25 to 85	LM239	
LM239DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU   SN	N / A for Pkg Type	-25 to 85	LM239N	Samples
LM239NE4	ACTIVE	PDIP	N	14	25	TBD	Call TI	Call TI	-25 to 85		Samples
LM239PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-25 to 85	L239	
LM239PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWRG4	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-25 to 85	L239	
LM2901AVQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQDRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material <sup>(6)</sup>	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM2901AVQPWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901BIDR	ACTIVE	SOIC	D	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901B	Samples
LM2901BIPWR	ACTIVE	TSSOP	PW	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901B	Samples
LM2901BIRTER	ACTIVE	WQFN	RTE	16	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	M2901B	Samples
LM2901D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125	LM2901	
LM2901DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRG3	ACTIVE	SOIC	D	14	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM -40 to 125		LM2901	Samples
LM2901N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type -40 to 125		LM2901N	Samples
LM2901NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	L2901	
LM2901PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901PWRG3	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901VQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQPWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM339AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LM339A	
LM339ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADRG4	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LM339A	





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM339AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU   SN	N / A for Pkg Type	0 to 70	LM339AN	Samples
LM339ANE4	ACTIVE	PDIP	N	14	25	TBD	Call TI	Call TI	0 to 70		Samples
LM339ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339APW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	0 to 70	L339A	
LM339APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339BIDR	ACTIVE	SOIC	D	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM339B	Samples
LM339BIPWR	ACTIVE	TSSOP	PW	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM339B	Samples
LM339BIRTER	ACTIVE	WQFN	RTE	16	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM339B	Samples
LM339D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LM339	
LM339DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU   SN	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NE3	ACTIVE	PDIP	N	14	25	RoHS & Non-Green	SN	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	0 to 70	L339	
LM339PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRE4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRG3	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	L339	Samples

# **PACKAGE OPTION ADDENDUM**

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM339PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF LM139, LM239A, LM2901, LM2901AV, LM2901B, LM2901V:

Automotive: LM239A-Q1, LM2901-Q1, LM2901AV-Q1, LM2901B-Q1, LM2901V-Q1

# **PACKAGE OPTION ADDENDUM**

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● Enhanced Product : LM239A-EP

• Space : LM139-SP

#### NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

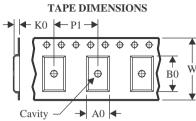
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application



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# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM139ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM139ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM139DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM139DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901BIDR	SOIC	D	14	3000	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901BIPWR	TSSOP	PW	14	3000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901BIRTER	WQFN	RTE	16	5000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
LM2901DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM2901DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2901DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM2901PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM339APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339BIDR	SOIC	D	14	3000	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339BIPWR	TSSOP	PW	14	3000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339BIRTER	WQFN	RTE	16	5000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
LM339DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM339PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM139ADR	SOIC	D	14	2500	350.0	350.0	43.0
LM139ADRG4	SOIC	D	14	2500	350.0	350.0	43.0
LM139DR	SOIC	D	14	2500	350.0	350.0	43.0
LM139DRG4	SOIC	D	14	2500	350.0	350.0	43.0
LM239ADR	SOIC	D	14	2500	353.0	353.0	32.0
LM239ADR	SOIC	D	14	2500	356.0	356.0	35.0
LM239DR	SOIC	D	14	2500	353.0	353.0	32.0
LM239PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2901AVQPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2901AVQPWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2901BIDR	SOIC	D	14	3000	356.0	356.0	35.0
LM2901BIPWR	TSSOP	PW	14	3000	356.0	356.0	35.0
LM2901BIRTER	WQFN	RTE	16	5000	367.0	367.0	35.0
LM2901DR	SOIC	D	14	2500	353.0	353.0	32.0
LM2901DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM2901DRG4	SOIC	D	14	2500	356.0	356.0	35.0
LM2901DRG4	SOIC	D	14	2500	353.0	353.0	32.0
LM2901NSR	SO	NS	14	2000	356.0	356.0	35.0



# **PACKAGE MATERIALS INFORMATION**

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2901PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2901PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2901PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2901VQPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2901VQPWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM339ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
LM339ADR	SOIC	D	14	2500	353.0	353.0	32.0
LM339ANSR	so	NS	14	2000	356.0	356.0	35.0
LM339APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM339APWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM339BIDR	SOIC	D	14	3000	356.0	356.0	35.0
LM339BIPWR	TSSOP	PW	14	3000	356.0	356.0	35.0
LM339BIRTER	WQFN	RTE	16	5000	367.0	367.0	35.0
LM339DBR	SSOP	DB	14	2000	356.0	356.0	35.0
LM339DR	SOIC	D	14	2500	353.0	353.0	32.0
LM339DRG4	SOIC	D	14	2500	356.0	356.0	35.0
LM339DRG4	SOIC	D	14	2500	353.0	353.0	32.0
LM339NSR	so	NS	14	2000	356.0	356.0	35.0
LM339PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM339PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LM239N	N	PDIP	14	25	506	13.97	11230	4.32
LM239N	N	PDIP	14	25	506.1	9	600	5.4
LM2901N	N	PDIP	14	25	506	13.97	11230	4.32
LM339AN	N	PDIP	14	25	506	13.97	11230	4.32
LM339AN	N	PDIP	14	25	506	13.97	11230	4.32
LM339AN	N	PDIP	14	25	506.1	9	600	5.4
LM339AN	N	PDIP	14	25	506	13.97	11230	4.32
LM339N	N	PDIP	14	25	506	13.97	11230	4.32
LM339N	N	PDIP	14	25	506	13.97	11230	4.32
LM339N	N	PDIP	14	25	506.1	9	600	5.4
LM339N	N	PDIP	14	25	506	13.97	11230	4.32
LM339NE3	N	PDIP	14	25	506.1	9	600	5.4
LM339NE4	N	PDIP	14	25	506	13.97	11230	4.32
LM339NE4	N	PDIP	14	25	506	13.97	11230	4.32
LM339NE4	N	PDIP	14	25	506	13.97	11230	4.32

3 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





PLASTIC QUAD FLATPACK - NO LEAD



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



PLASTIC QUAD FLATPACK - NO LEAD



- 4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-150.





- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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